Volume XXIX | October 2017

Assembly Solutions

Waffle Pack Sector Plate Shuttle

MRSI's die bonders offer the largest number of waffle packs in the industry. A three sector plate shuttle is available to provide additional waffle pack capability. Sector plates are attached to a linear shuttle mechanism. When used in conjunction with a rear sector plate the MRSI-705 can accommodate ninety six (96) 2" by 2" waffle packs/Gel-Paks. The MRSI-M3 can accommodate seventy two (72) waffle packs/Gel-Paks.

Waffle Pack Sector Plate Covers

Sector plate covers provide the means to cover the open waffle pack and Gel-Paks on a sector plate for storage and identification on the system. The sector plate cover has two tiers. The first tier holds the waffle packs. The top of the sector plate cover holds the waffle pack and Gel-Pak lids so the user can reference the die part number information. The sector plate cover is made of clear static dissipative material for ESD control.

Our systems can be configured based upon your application specific requirements. Contact MRSI today to learn more about configurable options on our die bonding systems.

Visit our Website

Visit MRSI Systems at Productronica in Munich, Germany

Visit us!
Hall B2, Stand 401

productronica 2017
November 14–17, 2017, Messe München

Productronica is the world's leading international trade fair for innovative electronics production. The 41st Productronica trade show will be held November 14-17, 2017 in Munich, Germany at Messe Munchen. MRSI Systems will be exhibiting at Productronica - Hall B2 Stand 401. Visit MRSI Systems in Hall B2 the Future Markets Cluster. Productronica is the "largest microelectronics event in Europe." Read the latest news

from Productronica. There will be over 1,100 exhibitors and 37,000 visitors from 85 countries with companies from all sectors of the electronics-manufacturing industry.

Contact MRSI to Schedule a Meeting

MRSI Blog - Weekly Insights into the Advanced Electronic Packaging Industry

- **High-Volume Manufacturing (HVM) of Photonics Devices – Success Requires Expertise in Eutectic Bonding of Chip on Submount (CoS)**
- **MRSI Systems Customer Support Team – Ezer Espares**
- **How to Choose a Die Bonder System**

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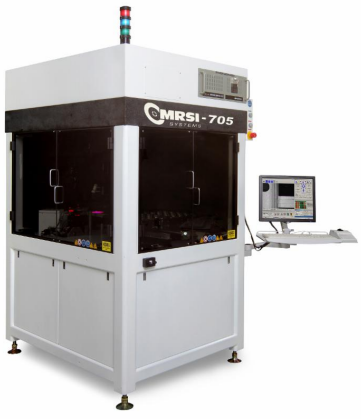
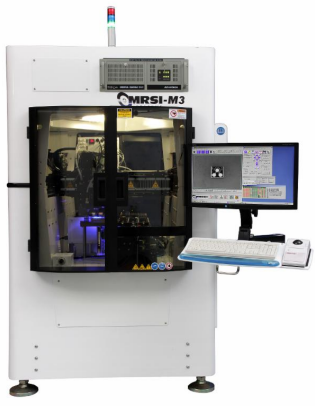
NEW PRODUCT
MRSI-HVM3
3-MICRON DIE BONDER

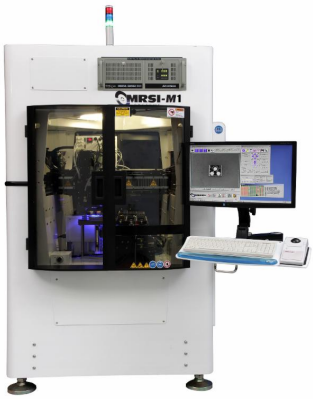


MRSI-705
5-MICRON DIE BONDER



MRSI-M3
3-MICRON DIE BONDER

MRSI-175Ag
EPOXY DISPENSER



MRSI-M1
1-MICRON DIE BONDER

MRSI Systems | 978-667-9449 | sales@mrsisystems.com
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Need More Information, Please contact us at:
sales@mrsisystems.com
+1-978-667-9449

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